



Form No.: QF-1274
Edition: 2

ISO9001 ISO14001 IATF16949 CHILISIN ELECTRONICS CORP.

RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer : 鴻海

Customer P/N:

Drawing No : A0X2002582

Quantity : 0 Pcs. Date : 2020/12/1

Chilisin P/N : BPPM00090770152X0F

SPECIFICATION ACCEPTED BY:

COMPONENT
ENGINEER

ELECTRICAL
ENGINEER

MECHANICAL
ENGINEER

APPROVED

REJECTED

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Checked by
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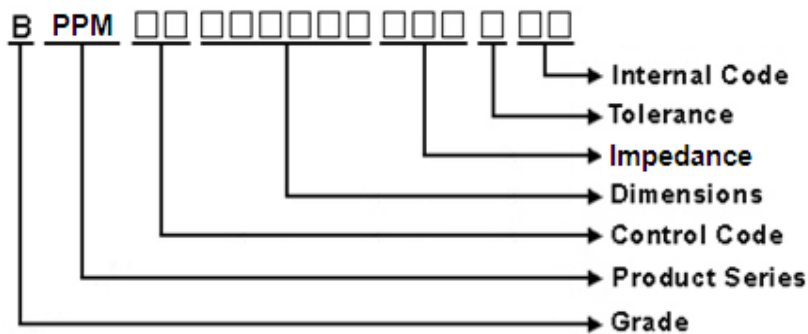


ISO9001 ISO14001 IATF16949 CHILISIN ELECTRONICS CORP.

BPPM00090770 Series Specification

1 Scope: This specification applies to the Pb Free high current type SMD Common mode filter

2 Part Numbering:



3 Rating:

Operating Temperature: $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$

4 Marking:



Ex Marking :152

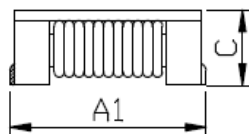
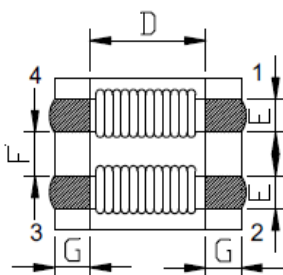
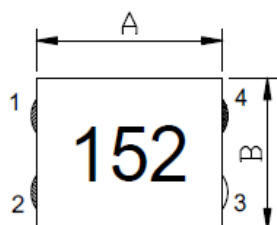
Marking color : Black

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

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6 Configuration and Dimensions:



A:	9.0±0.5	mm
A1:	9.5±0.5	mm
B:	7.0±0.5	mm
C:	7.0 Max.	mm
D:	5.6 Typ.	mm
E:	1.5±0.2	mm
F:	2.0±0.2	mm
G:	1.7±0.2	mm

7 Electrical Characteristics:

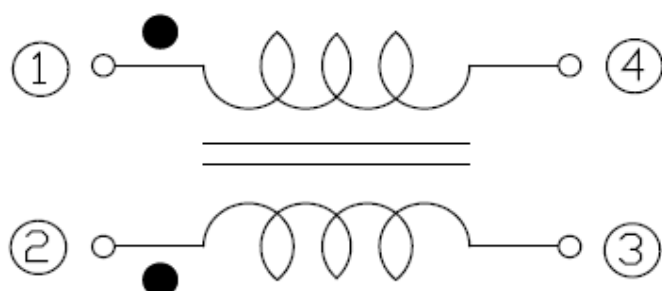
Part No.	Impedance(Ω) at 2.52MHz		Resistance RDC(mΩ) Max.(1 line)	Rated Current (A) Max.	Insulation Resistance (MΩ) Min.	Rated Voltage (V)Max.	Marking
	Min.	Typ.					
BPPM00090770152X0F	600	1500	50	3.5	10	80	152

NOTE:

1. Operating temperature range — 40°C ~ 125°C (Including self - temperature rise)
2. Rated Current : Based on temperature rise (ΔT : 40°C TYP.)

BPPM00090770 Series Specification

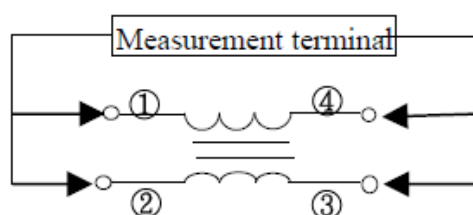
CHARACTERISTICS(REFERENCE)



TEST EQUIPMENT

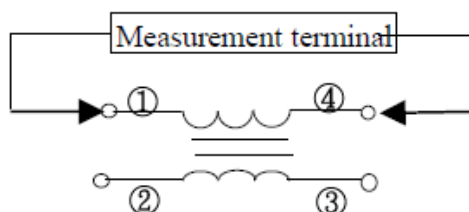
1 Impedance

Measured by HP4291B RF Impedance Analyzer.



2 DC Resistance

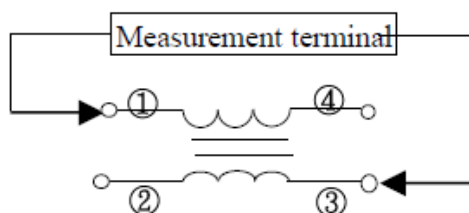
Measured by Chroma 16502 milliohm meter.



3 Insulation Resistance

Measured by Chroma 19073

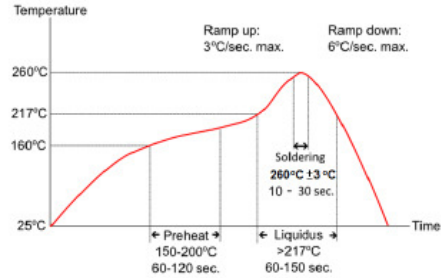
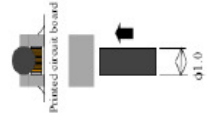
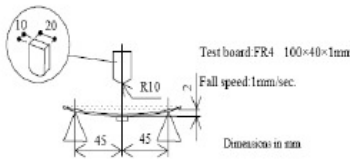
Measurement voltage : 50V ,Measurement time : 3 sec.



BPPM00090770 Series Specification

RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Solder ability	The product shall be connected to the test circuit board by the fillet (the height is 0.2mm).	Apply cream solder to the printed circuit board . Refer to clause 8 for Reflow profile.
Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Temperature profile of reflow soldering  Ramp down rate: 6°C per second (max.) Preheat temperature: 150-200°C, 60-120 seconds Liquidus temperature: above 217°C, 60-150 seconds Peak temperature: 260°C ± 3°C, 10-30 seconds Note: 1. Re-Flow Possible times: within 2 times 2. Nitrogen adopted is recommended while in re-flow
Terminal strength	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate , and then laterally apply a load 9.8N in the arrow direction. 
Strength on PC board bending	The terminal electrode and the ferrite must not damaged.	Solder a chip to test substrate and then apply a load. 
High temperature resistance	Impedance: Within ±20% of the initial value. Insulation resistance and DC resistance on the specification (refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board, the test shall be done. Measurement : After placing for 24 hours min. Temperature : +125±2°C Applied voltage : Rated voltage Applied current : Rated current Testing time : 500±12 hours

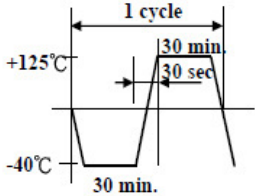


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BPPM00090770 Series Specification

RELIABILITY TEST METHOD

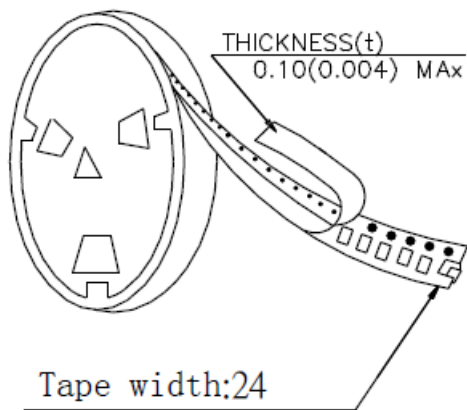
MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity resistance	Impedance: Within $\pm 20\%$ of the initial value. Insulation resistance and DC resistance on the specification (refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not be damaged.	After the samples shall be soldered onto the test circuit board, the test shall be done. Measurement : After placing for 24 hours min. Temperature : $+60 \pm 2^\circ\text{C}$, Humidity : 90 to 95 %RH Applied voltage : Rated voltage Applied current : Rated current Testing time : 500 ± 12 hours
Thermal shock	Impedance: Within $\pm 20\%$ of the initial value. Insulation resistance and DC resistance on the specification (refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not be damaged.	 1 cycle $+125^\circ\text{C}$ 30 min. 30 sec -40°C 30 min.
Low temperature storage	Impedance: Within $\pm 20\%$ of the initial value. Insulation resistance and DC resistance on the specification (refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not be damaged.	After the samples shall be soldered onto the test circuit board, the test shall be done. Measurement : After placing for 24 hours min. Temperature : $-40 \pm 2^\circ\text{C}$ Testing time : 500 ± 12 hours
Vibration	Impedance: Within $\pm 20\%$ of the initial value. Insulation resistance and DC resistance on the specification (refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not be damaged.	After the samples shall be soldered onto the test circuit board, the test shall be done. Frequency : 10 to 55 Hz Amplitude : 1.52 mm Dimension and times : X , Y and Z directions for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol (JIS-K-1522)) shall be coated over the whole of the sample before hand, the sample shall then be preheated for about 2 minutes in a temperature of $130 \sim 150^\circ\text{C}$ and after it has been immersed to a depth of 0.5mm below for 3 ± 0.2 seconds fully in molten solder M705 with a temperature of $245 \pm 2^\circ\text{C}$. More than 75% of the electrode sections shall be covered with new solder smoothly when the sample is taken out of the solder bath.

BPPM00090770 Series Specification

8 Packaging:

8.1 Packaging -Cover Tape

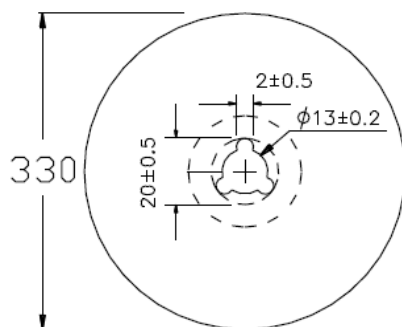


8.2 Packaging Quantity

TYPE	PCS/REEL
090770	600

8.3 Reel Dimensions

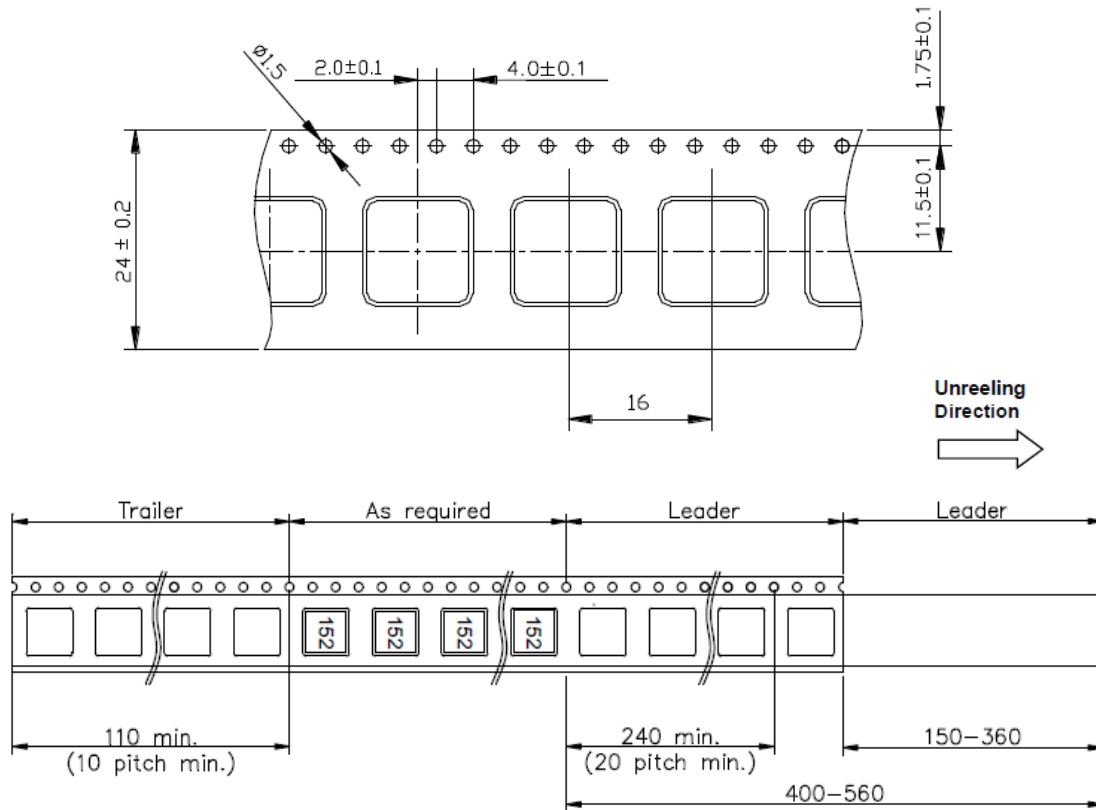
Unit : mm



BPPM00090770 Series Specification

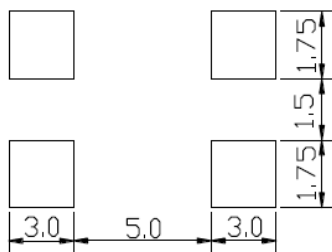
8 Packaging:

8.4 Tape Dimensions in mm



9 Recommended Land Pattern:

(STANDARD PATTERN) Unit:mm



10 Note:

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Do not knock or drop.
3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
5. The moisture sensitivity level (MSL) of products is classified as level 1.



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BPPM00090770 Series Specification

Curve:BPPM00090770152X0F

